

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Reissue of Patent No.: 6,296,503

Issued: October 2, 2001

Hideo SHIMADA et al.

Group Art Unit:

Filed:

Examiner:

For: IC SOCKET FOR ELECTRICAL PARTS WITH IMPROVED ELECTRICAL CONTACT

REISSUE DECLARATION UNDER 37 C.F.R. § 1.175

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

We, Hideo Shimada and Mori Kentaro, declare that:

1. Our residence, post office addresses and citizenships are as stated below next to our names.

2. We believe we are the original, first and joint inventors of the subject matter which is described and claimed in U.S. Letters Patent No. 6,296,503 ("503 patent") granted on October 2, 2001, and for which invention we solicit a reissue patent on the invention entitled IC SOCKET FOR ELECTRICAL PARTS WITH IMPROVED ELECTRICAL CONTACT, the specification of which is attached hereto.

3. We hereby state that we have reviewed and understand the contents of the above-identified specification, including the claims as amended in the attached reissue application.

4. We acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information which is material to patentability as defined in Title 37, Code of Federal Regulations, Section 1.56.

5. We hereby claim foreign priority benefit under Title 35, United States Code, Section 119, of Japanese Patent Application No. 9-287963 filed October 3, 1997 and Japanese Patent Application No. 9-344024 filed November 28, 1997, and there are no other foreign applications for patent or inventor's certificate having a filing date before Japanese Patent Application Numbers 9-287963 and 9-344024 on which priority is claimed.

6. We verily believe the original '503 patent to be wholly or partly inoperative or invalid by reason of patentees' claiming more or less than they had the right to claim in the patent.

7. With respect to the claims, one error relied upon as the basis for the reissue is the failure to claim a "method of mounting an electrical part" as claimed in claim 13.

8. All errors including those listed above, which are being corrected up to the time of filing this reissue declaration, arose without any deceptive intention on the part of the applicant.

9. We hereby appoint the following attorneys and/or agents to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

James D. Halsey, Jr., Reg. No. 22,729; Harry John Staas, Reg. No. 22,010; David M. Pitcher, Reg. No. 25,908; John C. Garvey, Reg. No. 28,607; J. Randall Beckers, Reg. No. 30,358; William F. Herbert, Reg. No. 31,024; Richard A. Gollhofer, Reg. No. 31,106; Mark J. Henry, Reg. No. 36,162; Paul I. Kravetz, Reg. No. 35,230; Gene M. Garner II, Reg. No. 34,12; Michael D. Stein, Reg. No. 37,240; Jon H. Muskin, Reg. No. 43,824, Stephen Boughner, Reg. No. 45,317, John H. Stowe, Reg. No. 32,863, C. Joan Gilsdorf, Reg. No. 43,635, Mehdi Sheikerz, Reg. No. 41,307, James G. McEwen, Reg. No. 41,983, Michael J. Badagliacca, Reg. No. 39,099, Heath E. Wells, Reg. No. 43,257, James T. Strom, Reg. No. 48,702, Eric Berkowitz, Reg. No. 44,030, Patrick J. Stanzione, Reg. No. 40,434, Charles Y. Park, Reg. No. P-50, 709, Matthew Q. Ammon, Reg. No. 50,346, Derrick L. Fields, Reg. No., P-50,133, and Seungman Kim, Reg. No. 50,102.

Please send all correspondence related to the above-identified application to the following address:

STAAS & HALSEY
700 Eleventh Street, N.W.
Suite 500
Washington, D.C. 20001



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PATENT TRADEMARK OFFICE

10. We hereby declare that all statements made herein of our own knowledge are true, that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor Hideo SHIMADA

Inventor's Signature Hideo Shimada Date Jun. 28, 2002

Country of Citizenship Japan

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Post Office Address c/o Enplas Corporation, 30-1, Namiki 2-chome, Kawaguchi-shi, Saitama 332-0034 JAPAN

Second name of first inventor Kentaro MORI

Inventor's Signature Kentaro Mori Date Jun 28, 2002

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Docket No.: 1509.1021-RE

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**CONSENT OF ASSIGNEE TO FILING OF REISSUE APPLICATION
AND OFFER TO SURRENDER ORIGINAL PATENT**

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Petitioner, Kouhei KAWASHIMA (Authorized Officer of Enplas Corporation) represents that I am the President (Title) of the Assignee identified below owning the entire interest in the above-identified patent and am authorized by the Assignee to assent to the filing of the subject application for reissue of the subject U.S. Letters Patent 6,296,503 and to sign on behalf of the Assignee.

CONSENT OF ASSIGNEE AND STATEMENT UNDER 37 CFR §3.73(b)

Enplas Corporation, presently the assignee of the entire interest including all rights in the above-identified application, having its principal place of business at 30-1, Namiki 2-chome, Kawaguchi-shi, Saitama 332-0034 Japan, hereby consents to reissue of U.S. Letters Patent No. 6,296,503. The Assignment to Enplas Corporation was recorded at Reel 010192, Frame 0331, for the original application Serial No. 09/319,127 which was filed on June 1, 1999 for IC SOCKET FOR ELECTRICAL PARTS WITH IMPROVED ELECTRICAL CONTACT and which issued October 2, 2001 as U.S. Letters Patent No. 6,296,503. The evidentiary documents have been reviewed and it is certified that to the best of the assignee's knowledge and belief, title is in the assignee and the undersigned has the authority to act on the behalf of the assignee, Enplas Corporation.

Reissue of Patent No.: 6,296,503
Issued: October 2, 2001

OFFER TO SURRENDER

Pursuant to 37 C.F.R. § 1.178, Enplas Corporation hereby offers to surrender original U.S. Letters Patent 6,296,503.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. '1001, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Date: July 8, 2002



Name of Officer: Kouhei Kawashima
Office: President